

## AMENDMENTS TO THE CLAIMS

Claims 1-28. (Canceled)

29. (Currently Amended) A method of forming an equi-voltage surface for plating an object comprising:

providing a source material electrically connected to a first terminal of a power supply;

providing an object having a plurality of portions to be plated, the object electrically connected to a second terminal of the power supply;

providing lines of electric field which are directed to a surface of the object;

[[and]]

adjusting directing the lines of electric field through at least a pair of conductive perforated plates electrically connected to each other and disposed between the source material and the object to provide parallel lines of electric field terminating on the surface of the object; and

directing the lines of electric field through an insulating adjustment plate disposed between the object and the conductive perforated plate on the side of the object to affect the amount of lines of electric field reaching the object.

30. (Currently Amended) The method according to claim 29, wherein said ~~step of adjusting~~ step of directing the lines of electric field through the least a pair of conductive perforated plates also provides an equi-voltage surface on the surface of the object.

31. (Currently Amended) The method according to claim 29, wherein said ~~step of adjusting~~ step of directing the lines of electric field through the least a pair of conductive perforated plates also provides a uniform density of lines of electric field terminating on the surface of the object.

32. (Currently Amended) The method according to claim 29, wherein both said ~~step of~~ adjusting steps of directing the lines of electric field ~~[[is]]~~ are independent of said step of providing lines of electric field.

Claims 33-35. (Canceled)

36. (New) The method according to claim 29 further comprising a step of providing a plurality of windows in the insulating adjustment plate corresponding to a plurality of portions of the object to be plated.
37. (New) The method according to claim 36, wherein sizes and locations of said plurality of windows correspond to pattern densities of the plurality of portions of the object to be plated.
38. (New) The method according to claim 29, wherein the at least pair of conductive perforated plates is electrically separated from the source material and the object.
39. (New) The method according to claim 29 further comprising a step of providing the insulating adjustment plate disposed on the surface of the conductive perforated plate on the side of the object.
40. (New) The method according to claim 29 further comprising a step of providing the insulating adjustment plate in the vicinity of the object and not in contact with the object.
41. (New) The method according to claim 29 further comprising a step of immersing the source material, the object, the at least a pair of conductive perforated plates and the insulating adjustment plate in a plating tank filled with a plating solution.